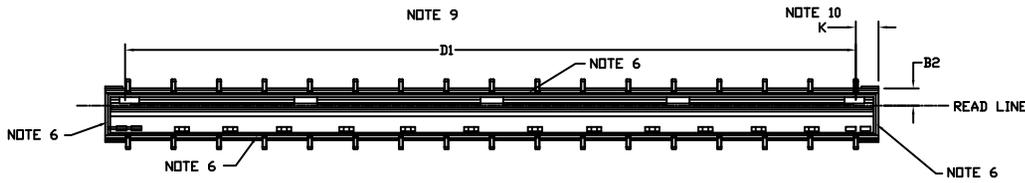


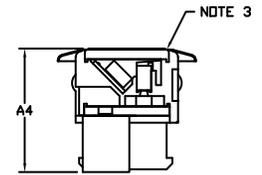


**IMAGE SENSOR MODULE**  
**CASE MODAJ**  
**ISSUE O**

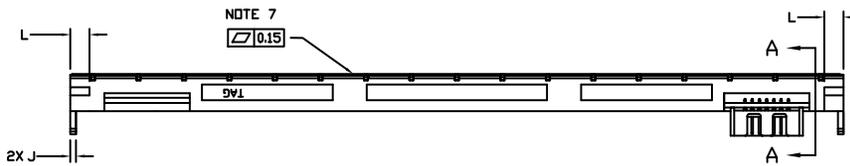
DATE 18 MAY 2010



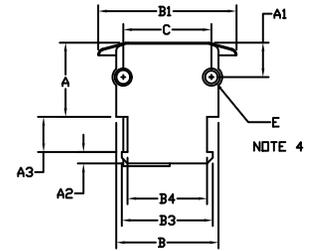
TOP VIEW



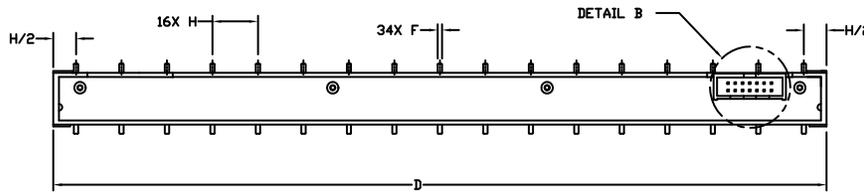
SECT. A-A  
2X SCALE



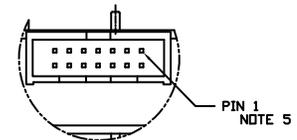
SIDE VIEW



END VIEW  
2X SCALE



BOTTOM VIEW



DETAIL B  
2X SCALE

DIM	MILLIMETERS	
	MIN	MAX
A	12.60	13.20
A1	5.63	5.93
A2	1.90	2.10
A3	5.98	6.18
A4	21.45	REF
B	17.70	18.30
B1	24.32	REF
B2	5.50	6.50
B3	15.85	16.15
B4	13.85	14.15
C	15.35	15.65
D	271.50	272.50
D1	256.00	REF
E	2.05	2.35
F	1.51	REF
H	16.00	REF
J	2.00	REF
K	7.00	9.00
L	6.80	REF

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING.
  4. BORE DEPTH IS 6.0.
  5. CONNECTOR, AMP MODEL NUMBER 103308-2, 2X7 PIN, PITCH 2.54.
  6. GLASS IS GLUED ON ALL 4 SIDES.
  7. GLASS THICKNESS IS 1.85.
  8. USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF-CM AND 2.00 KGF-CM.
  9. DIMENSION D1 DENOTES THE SCAN LENGTH.
  10. DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

<b>DOCUMENT NUMBER:</b>	<b>98AON51324E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>IMAGE SENSOR MODULE MODAJ</b>	<b>PAGE 1 OF 2</b>

